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Kind regards,

Team Nexperia



# PBSS301ND

20 V, 4 A NPN low  $V_{CEsat}$  (BISS) transistor

Rev. 03 — 7 September 2007

Product data sheet

## 1. Product profile

### 1.1 General description

NPN low  $V_{CEsat}$  Breakthrough in Small Signal (BISS) transistor in a SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package.

PNP complement: PBSS301PD.

### 1.2 Features

- Very low collector-emitter saturation resistance
- Ultra low collector-emitter saturation voltage
- 4 A continuous collector current
- Up to 15 A peak current
- High efficiency due to less heat generation

### 1.3 Applications

- Power management functions
- Charging circuits
- DC-to-DC conversion
- MOSFET gate driving
- Power switches (e.g. motors, fans)
- Thin Film Transistor (TFT) backlight inverter

### 1.4 Quick reference data

Table 1. Quick reference data

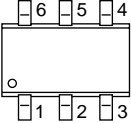
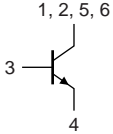
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CEO}$	collector-emitter voltage	open base	-	-	20	V
$I_C$	collector current		[1]	-	4	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	15	A
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = 4$ A; $I_B = 400$ mA	[2]	50	70	m $\Omega$

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

[2] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

**Table 2. Pinning**

Pin	Description	Simplified outline	Symbol
1	collector		
2	collector		
3	base		
4	emitter		
5	collector		
6	collector		

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		Version
	Name	Description	
PBSS301ND	SC-74	plastic surface-mounted package (TSOP6); 6 leads	SOT457

## 4. Marking

**Table 4. Marking codes**

Type number	Marking code
PBSS301ND	C6

## 5. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

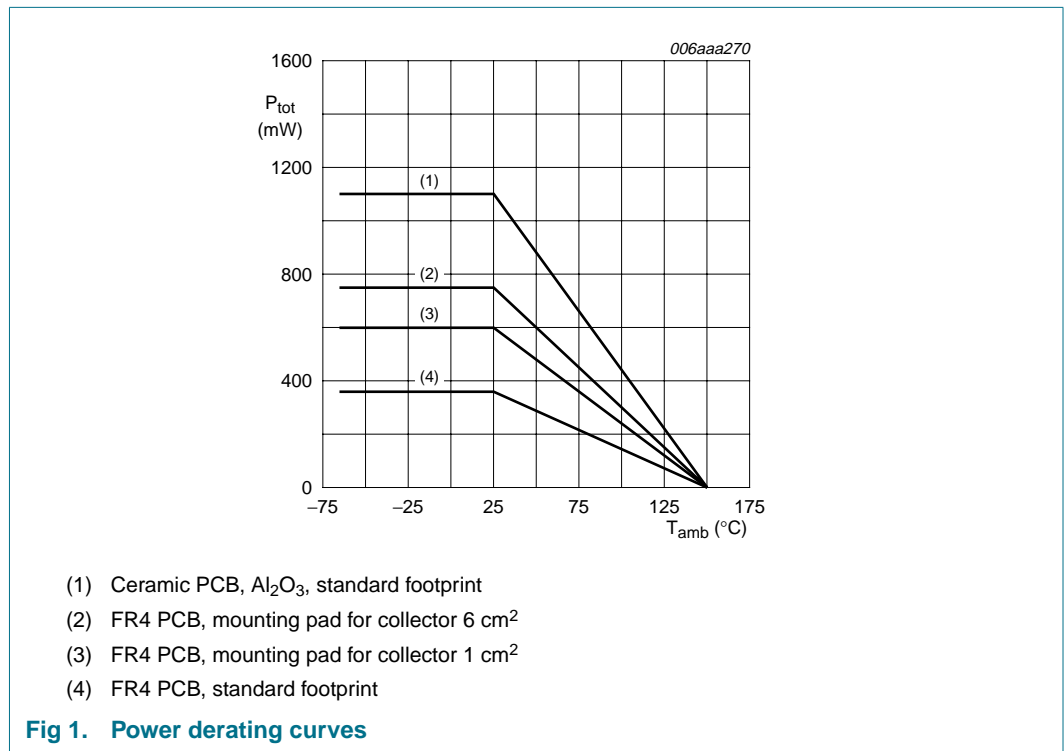
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	20	V
$V_{CEO}$	collector-emitter voltage	open base	-	20	V
$V_{EBO}$	emitter-base voltage	open collector	-	5	V
$I_C$	collector current		[1] -	4	A
$I_{CM}$	peak collector current	single pulse; $t_p \leq 1$ ms	-	15	A
$I_B$	base current		-	0.8	A
$I_{BM}$	peak base current	single pulse; $t_p \leq 1$ ms	-	2	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25$ °C	[2] -	360	mW
			[3] -	600	mW
			[4] -	750	mW
			[1] -	1.1	W
			[2][5] -	2.5	W

**Table 5. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C
$T_{stg}$	storage temperature		-65	+150	°C

- [1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1  $cm^2$ .
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6  $cm^2$ .
- [5] Operated under pulsed conditions: duty cycle  $\delta \leq 10\%$  and pulse width  $t_p \leq 10\text{ ms}$ .

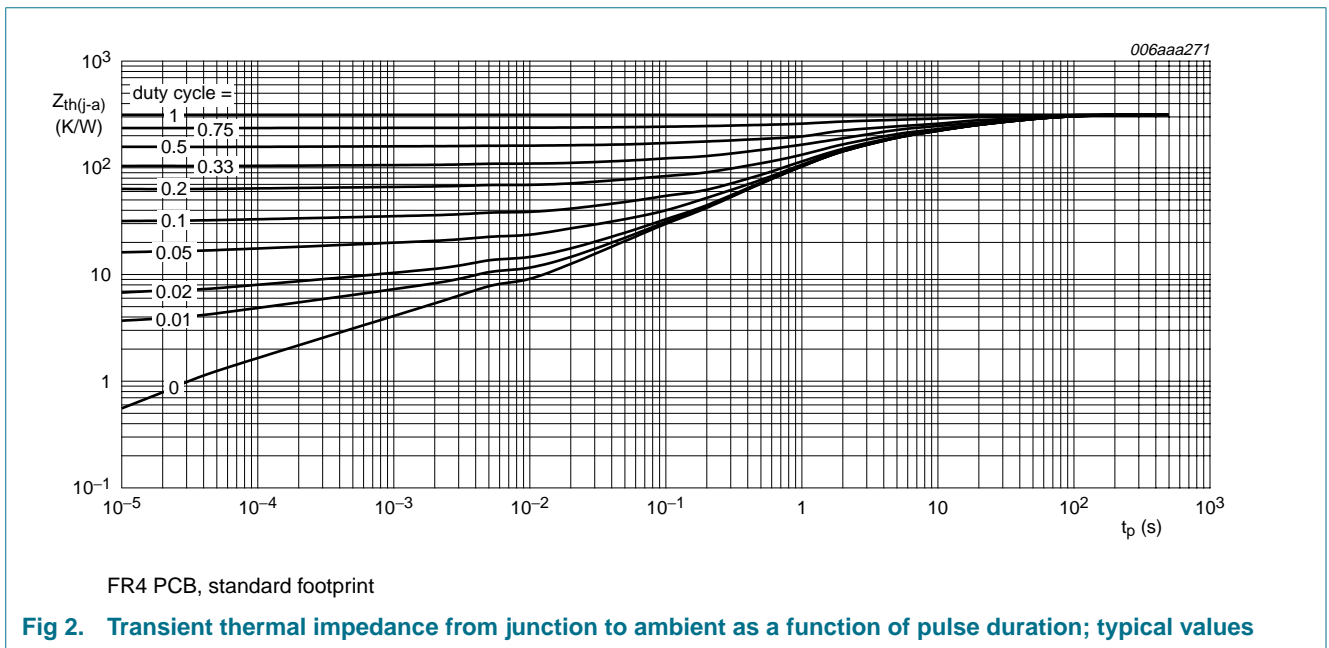


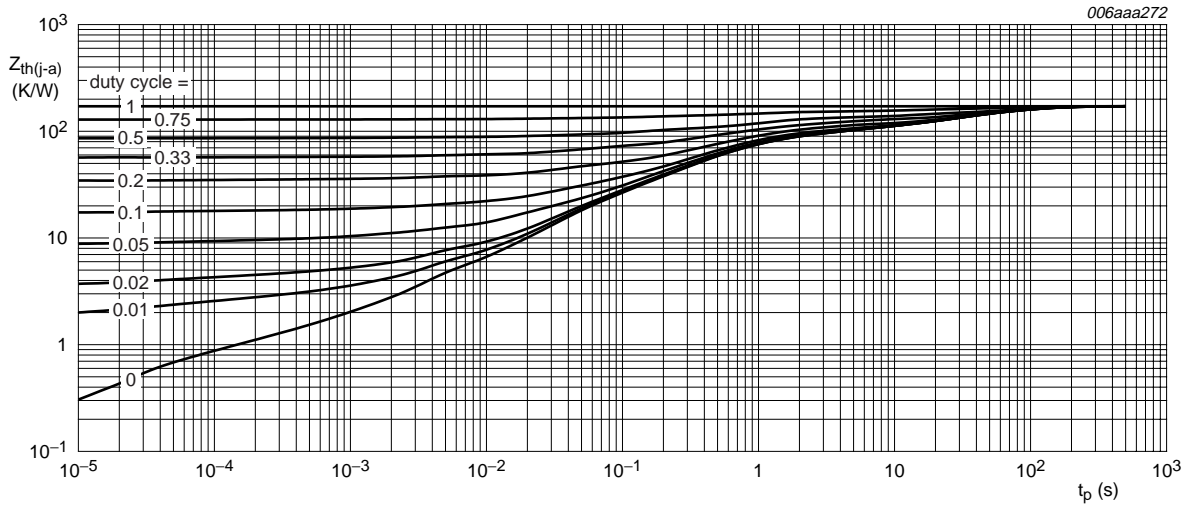
## 6. Thermal characteristics

**Table 6. Thermal characteristics**

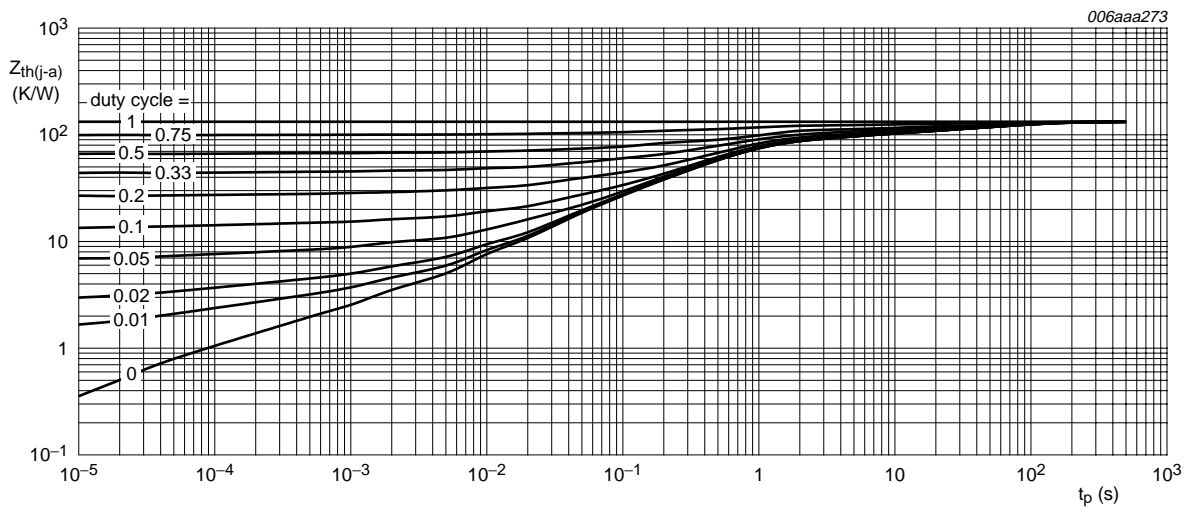
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[2]	-	-	350	K/W
			[3]	-	-	208	K/W
			[4]	-	-	167	K/W
			[1]	-	-	113	K/W
			[2][5]	-	-	50	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	45	K/W	

- [1] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1  $cm^2$ .
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6  $cm^2$ .
- [5] Operated under pulsed conditions: duty cycle  $\delta \leq 10\%$  and pulse width  $t_p \leq 10$  ms.





**Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



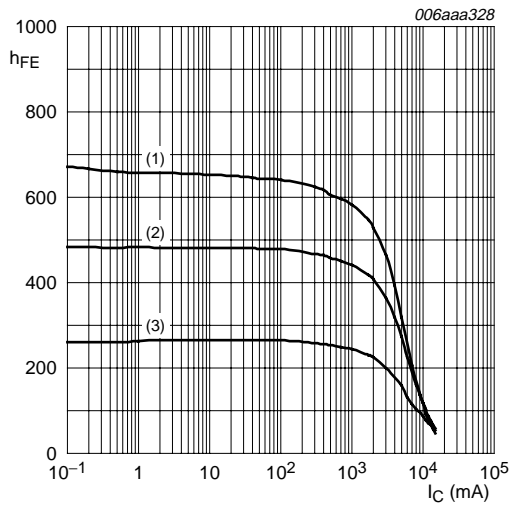
**Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

## 7. Characteristics

**Table 7. Characteristics**
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

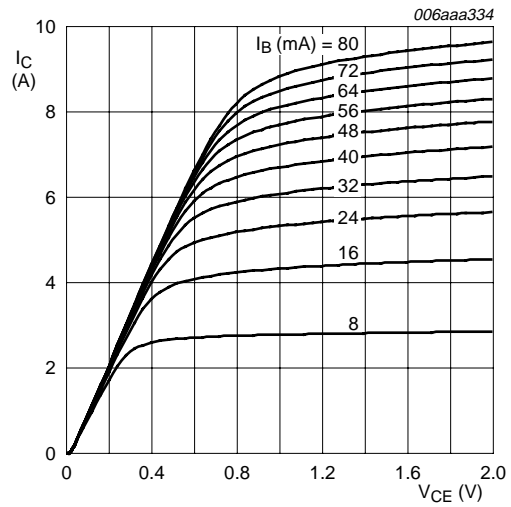
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$I_{CBO}$	collector-base cut-off current	$V_{CB} = 20\text{ V}; I_E = 0\text{ A}$	-	-	0.1	$\mu\text{A}$	
		$V_{CB} = 20\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	50	$\mu\text{A}$	
$I_{CES}$	collector-emitter cut-off current	$V_{CE} = 20\text{ V}; V_{BE} = 0\text{ V}$	-	-	0.1	$\mu\text{A}$	
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	0.1	$\mu\text{A}$	
$h_{FE}$	DC current gain	$V_{CE} = 2\text{ V}; I_C = 0.5\text{ A}$	300	450	-		
		$V_{CE} = 2\text{ V}; I_C = 1\text{ A}$	[1]	300	430	-	
		$V_{CE} = 2\text{ V}; I_C = 2\text{ A}$	[1]	250	400	-	
		$V_{CE} = 2\text{ V}; I_C = 4\text{ A}$	[1]	200	310	-	
		$V_{CE} = 2\text{ V}; I_C = 6\text{ A}$	[1]	100	230	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 0.5\text{ A}; I_B = 50\text{ mA}$	-	30	50	mV	
		$I_C = 1\text{ A}; I_B = 50\text{ mA}$	-	60	90	mV	
		$I_C = 2\text{ A}; I_B = 200\text{ mA}$	-	110	150	mV	
		$I_C = 4\text{ A}; I_B = 400\text{ mA}$	[1]	-	200	280	mV
		$I_C = 6\text{ A}; I_B = 600\text{ mA}$	[1]	-	300	420	mV
$R_{CEsat}$	collector-emitter saturation resistance	$I_C = 4\text{ A}; I_B = 400\text{ mA}$	[1]	-	50	70	m $\Omega$
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 0.5\text{ A}; I_B = 50\text{ mA}$	-	0.79	0.85	V	
		$I_C = 1\text{ A}; I_B = 50\text{ mA}$	-	0.81	0.9	V	
		$I_C = 1\text{ A}; I_B = 100\text{ mA}$	[1]	-	0.83	1	V
		$I_C = 4\text{ A}; I_B = 400\text{ mA}$	[1]	-	1.0	1.1	V
$V_{BEon}$	base-emitter turn-on voltage	$V_{CE} = 2\text{ V}; I_C = 2\text{ A}$	-	0.79	1	V	
$t_d$	delay time	$V_{CC} = 12.5\text{ V}; I_C = 3\text{ A}; I_{Bon} = 0.15\text{ A}; I_{Boff} = -0.15\text{ A}$	-	12	-	ns	
$t_r$	rise time		-	36	-	ns	
$t_{on}$	turn-on time		-	48	-	ns	
$t_s$	storage time		-	230	-	ns	
$t_f$	fall time		-	50	-	ns	
$t_{off}$	turn-off time		-	280	-	ns	
$f_T$	transition frequency	$V_{CE} = 10\text{ V}; I_C = 0.1\text{ A}; f = 100\text{ MHz}$	-	100	-	MHz	
$C_c$	collector capacitance	$V_{CB} = 10\text{ V}; I_E = I_e = 0\text{ A}; f = 1\text{ MHz}$	-	60	-	pF	

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .



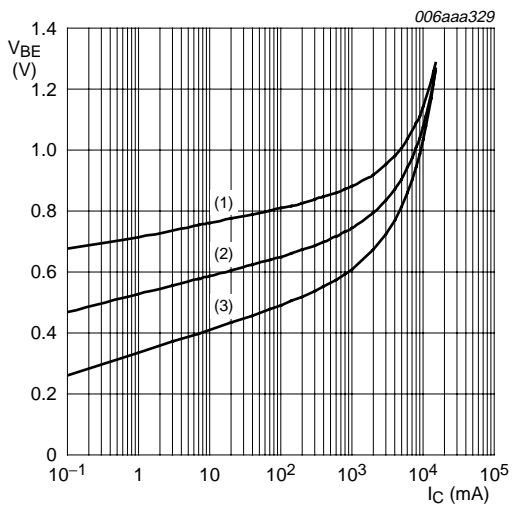
$V_{CE} = 2\text{ V}$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig 5. DC current gain as a function of collector current; typical values**



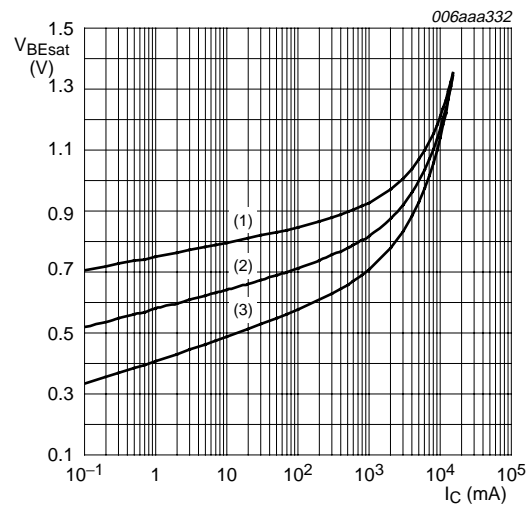
$T_{amb} = 25\text{ °C}$

**Fig 6. Collector current as a function of collector-emitter voltage; typical values**



$V_{CE} = 2\text{ V}$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

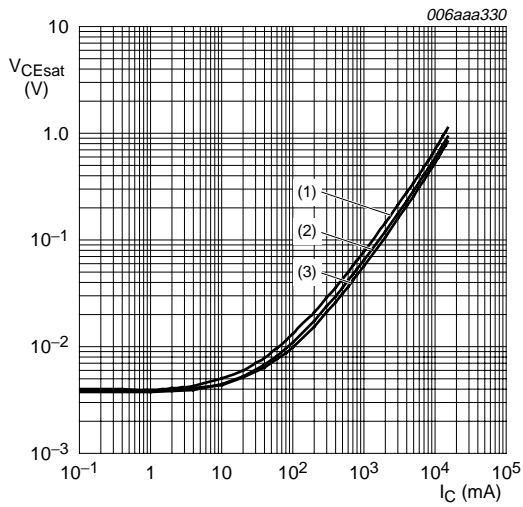
**Fig 7. Base-emitter voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = -55\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = 100\text{ °C}$

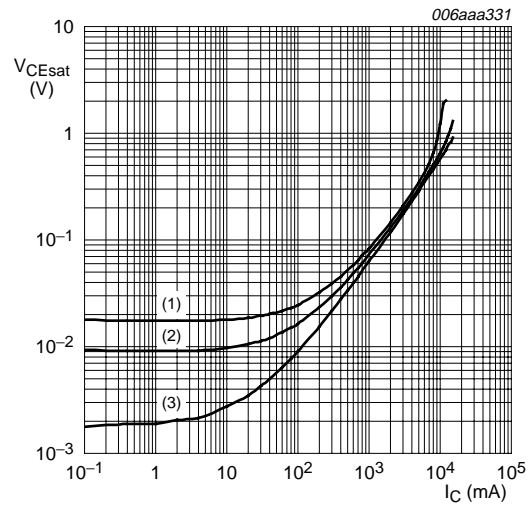
**Fig 8. Base-emitter saturation voltage as a function of collector current; typical values**





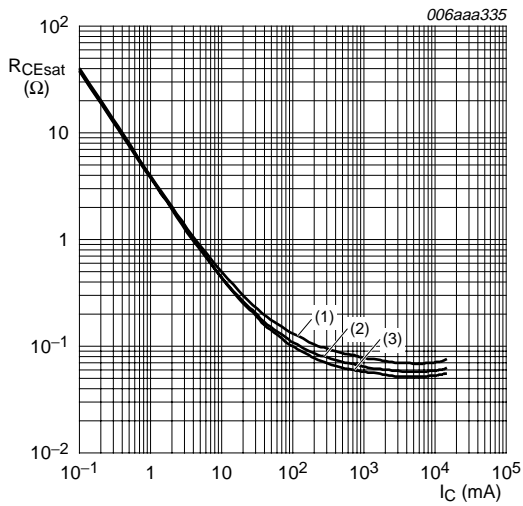
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

**Fig 9. Collector-emitter saturation voltage as a function of collector current; typical values**



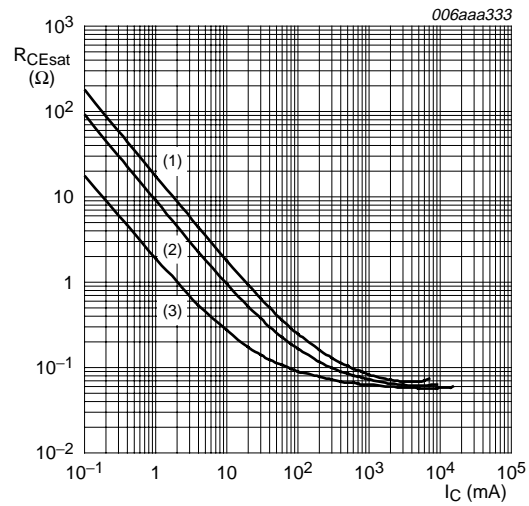
$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 100$   
 (2)  $I_C/I_B = 50$   
 (3)  $I_C/I_B = 10$

**Fig 10. Collector-emitter saturation voltage as a function of collector current; typical values**



$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -55\text{ °C}$

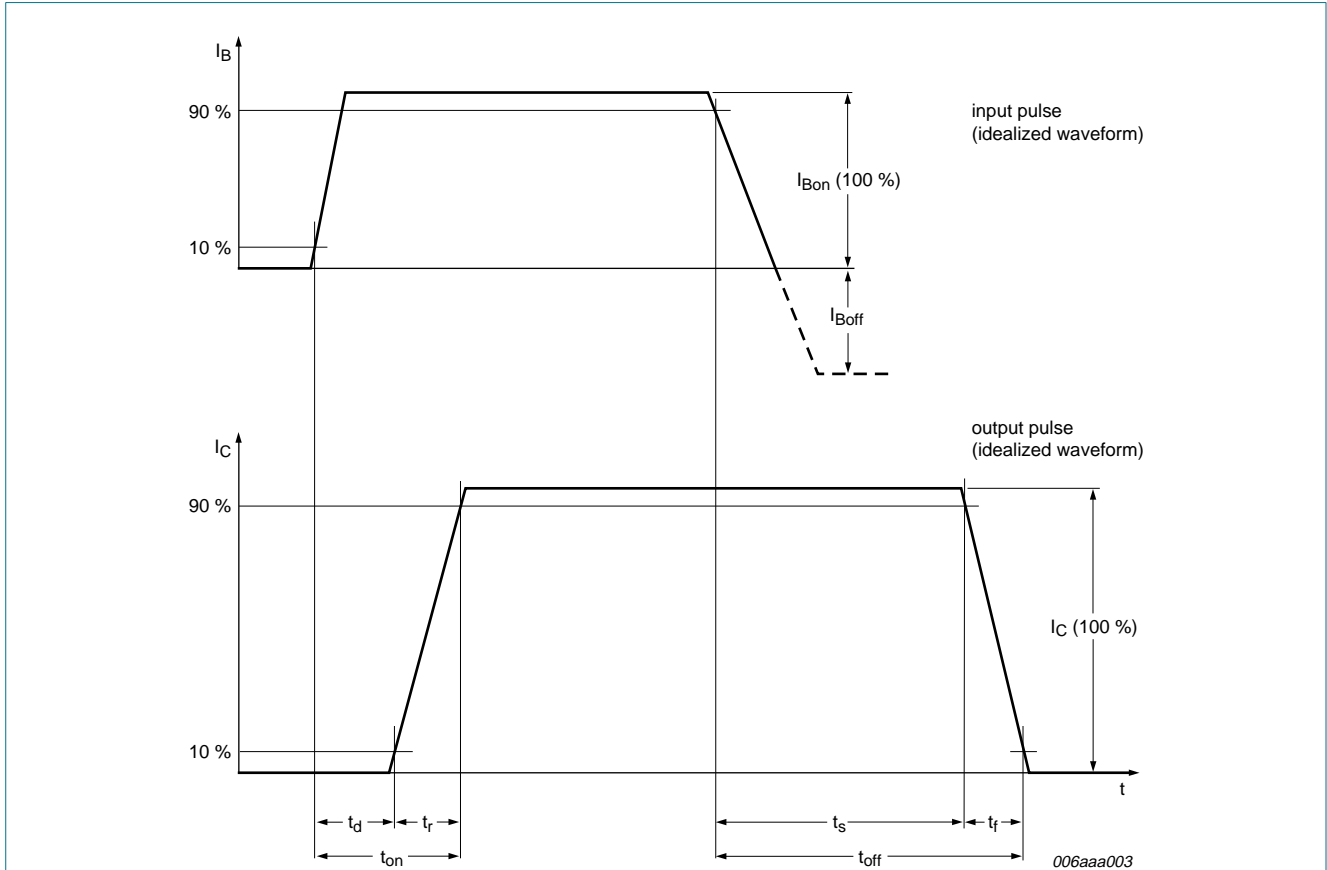
**Fig 11. Collector-emitter saturation resistance as a function of collector current; typical values**



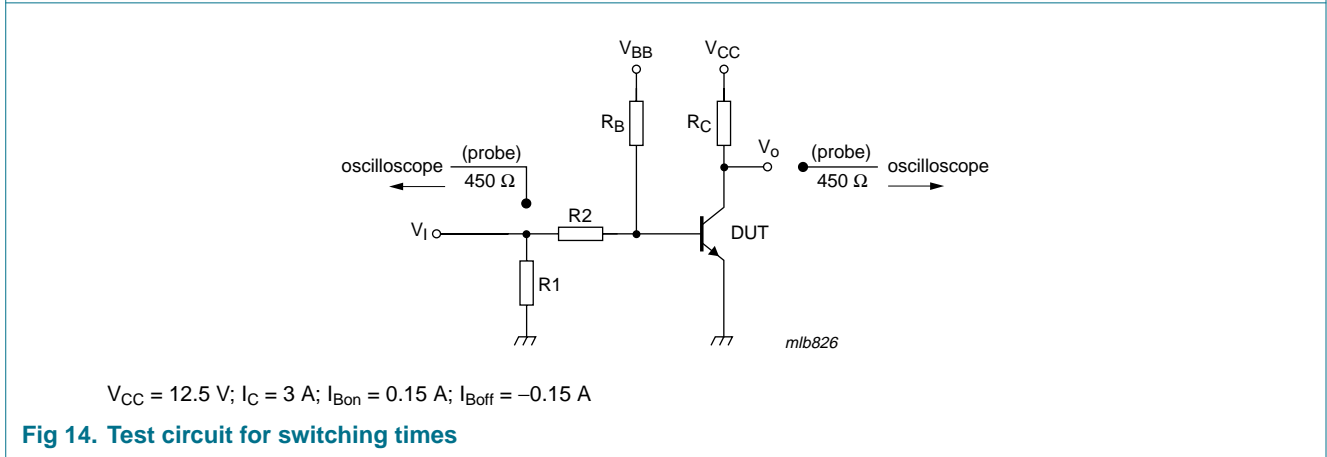
$T_{amb} = 25\text{ °C}$   
 (1)  $I_C/I_B = 100$   
 (2)  $I_C/I_B = 50$   
 (3)  $I_C/I_B = 10$

**Fig 12. Collector-emitter saturation resistance as a function of collector current; typical values**

**8. Test information**



**Fig 13. BISS transistor switching time definition**



**Fig 14. Test circuit for switching times**

## 9. Package outline

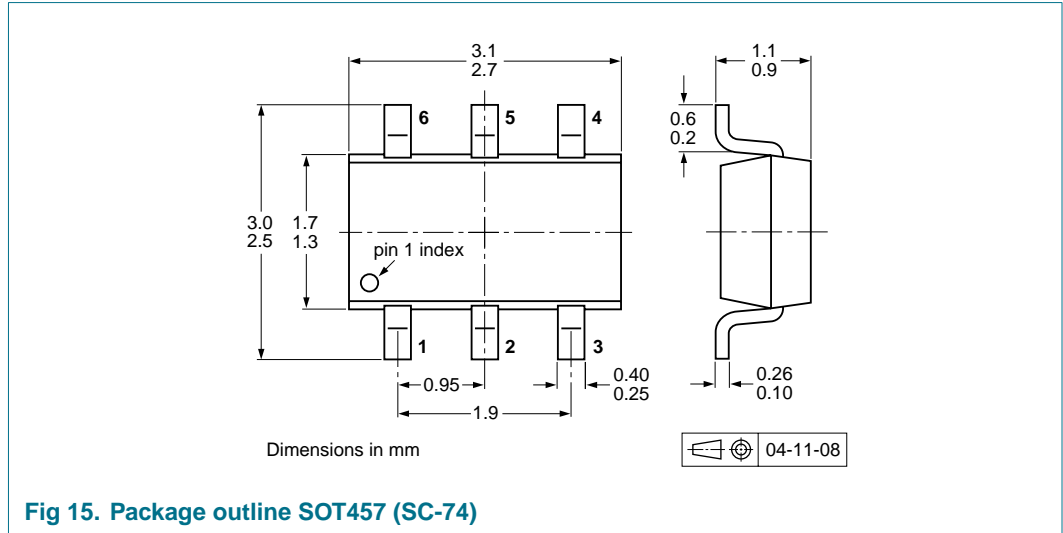


Fig 15. Package outline SOT457 (SC-74)

## 10. Packing information

**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

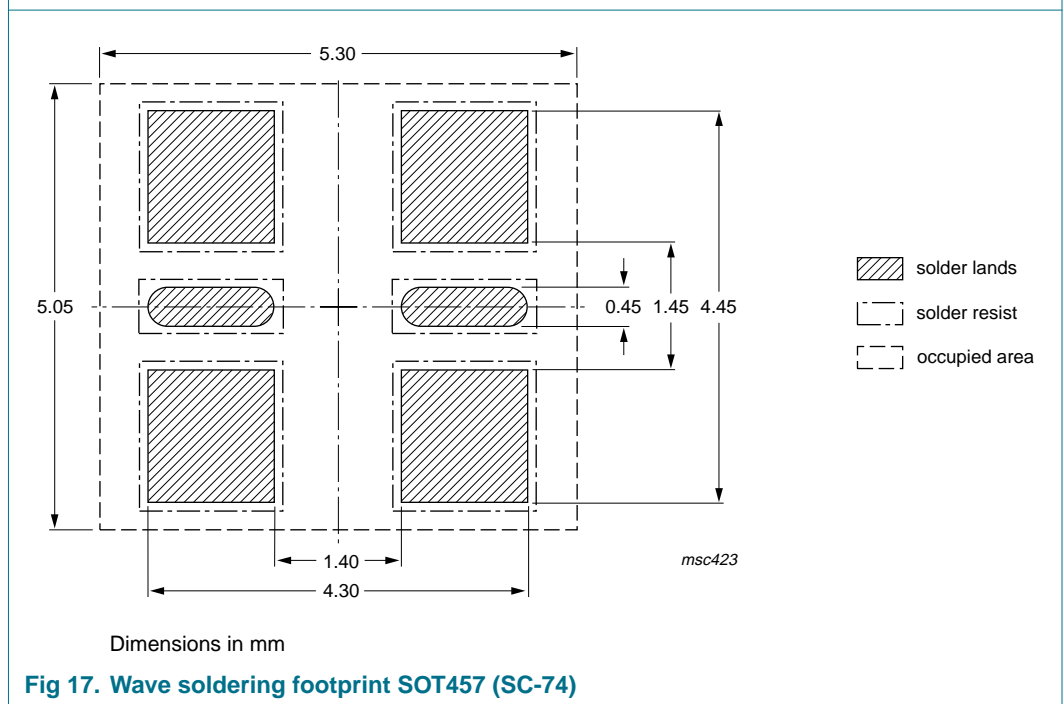
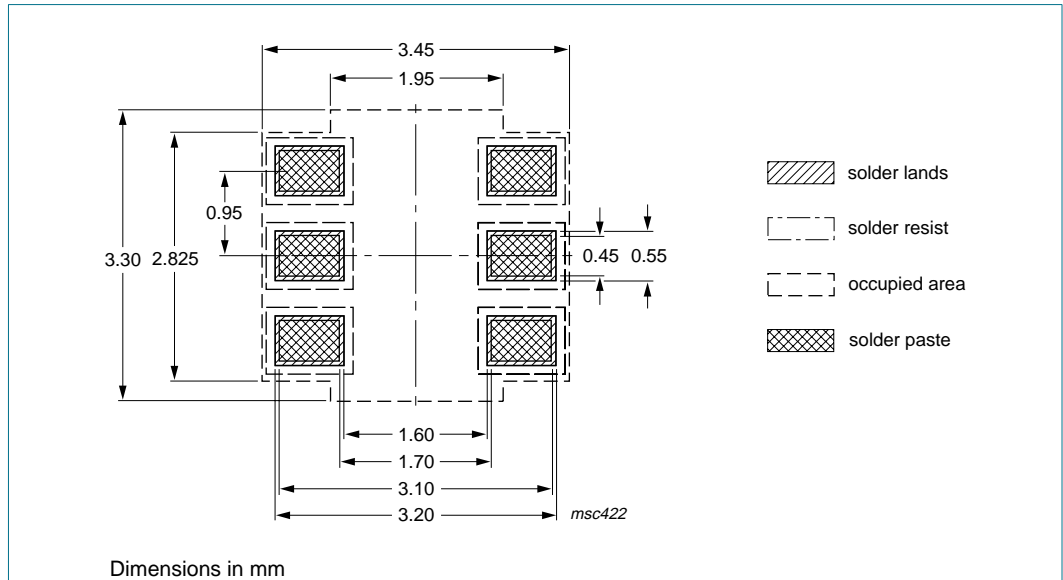
Type number	Package	Description	Packing quantity	
			3000	10000
PBSS301ND	SOT457	4 mm pitch, 8 mm tape and reel; T1	<sup>[2]</sup> -115	-135
		4 mm pitch, 8 mm tape and reel; T2	<sup>[3]</sup> -125	-165

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T2: reverse taping

## 11. Soldering



## 12. Revision history

**Table 9.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBSS301ND_3	20070907	Product data sheet	-	PBSS301ND_2
Modifications:		<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• <a href="#">Section 1.1 “General description”</a>: amended</li><li>• <a href="#">Table 6</a>: typing error for maximum value on 6 cm<sup>2</sup> footprint amended</li><li>• <a href="#">Figure 2</a>, <a href="#">3</a>, <a href="#">4</a>, <a href="#">6</a> and <a href="#">7</a>: amended</li><li>• <a href="#">Figure 15</a>: superseded by minimized package outline drawing</li><li>• <a href="#">Section 11 “Soldering”</a>: added</li><li>• <a href="#">Section 13 “Legal information”</a>: updated</li></ul>		
PBSS301ND_2	20050425	Product data sheet	-	PBSS301ND_1
PBSS301ND_1	20050405	Product data sheet	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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